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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c716-20i-so

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1.0 **DEVICE OVERVIEW**

This document contains device-specific information. Additional information may be found in the PIC[®] Mid-Range Reference Manual, (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

FIGURE 1-1.
FIGURE 1-1

There are two devices (PIC16C712, PIC16C716) covered by this data sheet.

Figure 1-1 is the block diagram for both devices. The pinouts are listed in Table 1-1.



Pin	PIC16C712/716		Pin	Buffer	
Name	DIP, SOIC	SSOP	Туре	Туре	Description
MCLR/VPP MCLR	4	4	I	ST	Master clear (Reset) input. This pin is an active low Reset to the device.
Vpp			Р		Programming voltage input
OSC1/CLKIN OSC1	16	18	I	ST	Oscillator crystal input or external clock source input. ST buffer when config-
CLKIN			I	CMOS	External clock source input.
OSC2/CLKOUT OSC2	15	17	О	_	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator
CLKOUT			Ο	_	In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
					PORTA is a bidirectional I/O port.
RA0/AN0 RA0 AN0	17	19	I/O I	TTL Analog	Digital I/O Analog input 0
RA1/AN1 RA1 AN1	18	20	I/O I	TTL Analog	Digital I/O Analog input 1
RA2/AN2 RA2 AN2	1	1	I/O I	TTL Analog	Digital I/O Analog input 2
RA3/AN3/VREF RA3 AN3 VREF	2	2	I/O I I	TTL Analog Analog	Digital I/O Analog input 3 A/D Reference Voltage input.
RA4/T0CKI RA4	3	3	I/O	ST/OD	Digital I/O. Open drain when configured
тоскі			I	ST	Timer0 external clock input

TABLE 1-1: PIC16C712/716 PINOUT DESCRIPTION

 Legend:
 TTL = TTL-compatible input
 CMOS = CMOS compatible input or output

 ST = Schmitt Trigger input with CMOS levels
 OD = Open drain output

 SM = SMBus compatible input. An external resistor is required if this pin is used as an output

 NPU = N-channel pull-up
 PU = Weak internal pull-up

 No-P diode = No P-diode to VDD
 AN = Analog input or output

 I = input
 O = output

 P = Power
 L = LCD Driver

2.2.2.2 OPTION_REG Register

The OPTION_REG register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 2-5: OPTION_REG REGISTER (ADDRESS 81h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	R = Readable bit
bit7							bit0	W = Writable bit
								read as '0'
								- n = Value at POR Reset
bit 7:	RBPU: PO	RTB Pull-	up Enabl	e bit				
	1 = PORTE	3 pull-ups	are disat	oled	المتعادية المعاط			
		s puil-ups	are enac	nea by Ina	ividual port	latch valu	es	
bit 6:	INTEDG: In	nterrupt E	dge Sele		nin			
	1 = Interruption = 0 = Interruption	pt on fallin	ig edge of	f RB0/INT	pin			
bit 5:	TOCS: TM	R0 Clock \$	Source S	elect bit				
	1 = Transit	ion on RA	4/T0CKI	pin				
	0 = Interna	I instruction	on cycle o	clock (CLK	(OUT)			
bit 4:	TOSE: TMF	R0 Source	e Edge Se	elect bit				
	1 = Increm	ent on hig	h-to-low	transition	on RA4/T00	CKI pin		
h:+ 0.								
DIT 3:	1 = Presca	ler is assi	aned to t	he WDT				
	0 = Prescaler is assigned to the Timer0 module							
bit 2-0:	PS2:PS0 :	Prescaler	Rate Sel	ect bits				
	Bit Value	TMR0 Ra	ate WD1	Rate				
	000	1:2	1:	1				
	001	1:4	1:	2				
	010	1:8	1:	4 8				
	100	1:32	1:	16				
	101	1:64	1:	32				
	110 111	1:128	B 1:	64 128				
		1.200	5 1					

2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts. **Note:** Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x			
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	R	= Readable bit	
bit7	·						bit0	W U -n	 Writable bit Unimplemented bit, read as '0' Value at POR Reset 	
bit 7:	GIE: Glob 1 = Enabl 0 = Disab	GIE: Global Interrupt Enable bit 1 = Enables all unmasked interrupts 0 = Disables all interrupts								
bit 6:	PEIE: Per 1 = Enabl 0 = Disab	PEIE : Peripheral Interrupt Enable bit 1 = Enables all unmasked peripheral interrupts 0 = Disables all peripheral interrupts								
bit 5:	TOIE : TMI 1 = Enabl 0 = Disab	TOIE : TMR0 Overflow Interrupt Enable bit 1 = Enables the TMR0 interrupt 0 = Disables the TMR0 interrupt								
bit 4:	IINTE: RE 1 = Enabl 0 = Disab	IINTE: RB0/INT External Interrupt Enable bit 1 = Enables the RB0/INT external interrupt 0 = Disables the RB0/INT external interrupt								
bit 3:	RBIE : RB Port Change Interrupt Enable bit 1 = Enables the RB port change interrupt 0 = Disables the RB port change interrupt									
bit 2:	TOIF : TMR0 Overflow Interrupt Flag bit 1 = TMR0 register has overflowed (must be cleared in software) 0 = TMR0 register did not overflow									
bit 1:	INTF: RB0/INT External Interrupt Flag bit 1 = The RB0/INT external interrupt occurred (must be cleared in software) 0 = The RB0/INT external interrupt did not occur									
bit 0:	RBIF : RB Port Change Interrupt Flag bit 1 = At least one of the RB7:RB4 pins changed state (must be cleared in software) 0 = None of the RB7:RB4 pins have changed state									

3.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PIC[®] Mid-Range Reference Manual, (DS33023).

3.1 PORTA and the TRISA Register

PORTA is a 5-bit wide bidirectional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input, (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output, (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, the value is modified, and then written to the port data latch. Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers.

PORTA pins, RA3:0, are multiplexed with analog inputs and analog VREF input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

Note:	On a Power-on Reset, these pins are
	configured as analog inputs and read as
	ʻ0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 3-1: INITIALIZING PORTA

BCF	STATUS, RPO	;
CLRF	PORTA	; Initialize PORTA by
		; clearing output
		; data latches
BSF	STATUS, RPC	; Select Bank 1
MOVLW	OxEF	; Value used to
		; initialize data
		; direction
MOVWF	TRISA	; Set RA<3:0> as inputs
		; RA<4> as outputs
BCF	STATUS, RPO	; Return to Bank 0

PIC16C712/716

FIGURE 3-1: BLOCK DIAGRAM OF RA3:RA0







5.3 Timer1 Oscillator

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator rated up to 200 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 5-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 5-2:CAPACITOR SELECTION FOR
THE TIMER1 OSCILLATOR

Osc Type	Freq.	C1	C2		
LP	32 kHz	33 pF	33 pF		
	100 kHz	15 pF	15 pF		
	200 kHz	15 pF	15 pF		
These values are for design guidance only.					
Note 1: Higher capacitance increases the stability of					

oscillator but also increases the start-up time.

2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

5.4 Timer1 Interrupt

The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

5.5 Resetting Timer1 using a CCP Trigger Output

If the CCP module is configured in Compare mode to generate a "Special Event Trigger" (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note:	The Special Event Triggers from the	э				
	CCP1 module will not set interrupt flag bi	t				
	TMR1IF (PIR1<0>).					

Timer1 must be configured for either Timer or Synchronized Counter mode to take advantage of this feature. If Timer1 is running in Asynchronous Counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a Special Event Trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPR1H:CCPR1L registers pair effectively becomes the period register for Timer1.

Value on Value on Address Name Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 1 Bit 0 POR, all other Bit 2 BOR Resets 0Bh,8Bh INTCON GIE PEIE TOIE INTE RBIE **T0IF** INTE RBIF 0000 000x 0000 000u -0---000 -0---000 0Ch PIR1 ADIF CCP1IF TMR2IF TMR1IF -0---000 -0---000 8Ch PIE1 ADIE CCP1IE TMR2IE TMR1IE 0Eh TMR1L Holding Register for the Least Significant Byte of the 16-bit TMR1 Register XXXX XXXX uuuu uuuu 0Fh TMR1H Holding Register for the Most Significant Byte of the 16-bit TMR1 Register XXXX XXXX uuuu uuuu --00 0000 --uu uuuu T1CKPS1 T1CKPS0 T1OSCEN T1SYNC 10h T1CON ____ ____ TMR1CS TMR10N -x-x _ _ _ _ -11-11 07h DATACC DCCP DT1CK Р ---- -1-1 ---- -1-1 87h TRISCCP TCCP TT1CK

TABLE 5-3: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Legend: x = unknown, u = unchanged, --- = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.

7.0 CAPTURE/COMPARE/PWM (CCP) MODULE(S)

Each CCP (Capture/Compare/PWM) module contains a 16-bit register, which can operate as a 16-bit capture register, as a 16-bit compare register or as a PWM master/slave Duty Cycle register. Table 7-1 shows the timer resources of the CCP module modes.

Capture/Compare/PWM Register 1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

FIGURE 7-1: CCP1CON REGISTER (ADDRESS 17h)

U-0 U-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 DC1B1 DC1B0 CCP1M3 CCP1M2 CCP1M1 CCP1M0 R = Readable bit W = Writable bit bit7 bit0 U = Unimplemented bit, read as '0' -n = Value at POR Reset bit 7-6: Unimplemented: Read as '0' bit 5-4: DC1B1:DC1B0: PWM Least Significant bits Capture Mode: Unused Compare Mode: Unused PWM Mode: These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPR1L. bit 3-0: CCP1M3:CCP1M0: CCP1 Mode Select bits 0000 = Capture/Compare/PWM off (resets CCP1 module) 0100 = Capture mode, every falling edge 0101 = Capture mode, every rising edge 0110 = Capture mode, every 4th rising edge 0111 = Capture mode, every 16th rising edge 1000 = Compare mode, set output on match (CCP1IF bit is set) 1001 = Compare mode, clear output on match (CCP1IF bit is set) 1010 = Compare mode, generate software interrupt on match (CCP1IF bit is set, CCP1 pin is unaffected) 1011 = Compare mode, trigger special event (CCP1IF bit is set; CCP1 resets TMR1 and starts an A/D conversion (if A/D module is enabled)) 11xx = PWM mode

FIGURE 7-2: TRISCCP REGISTER (ADDRESS 87H)



Additional information on the CCP module is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

TABLE 7-1:CCP MODE – TIMER
RESOURCE

Timer Resource
Timer1
Timer1
Timer2

7.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RB3/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

FIGURE 7-3:

CAPTURE MODE OPERATION BLOCK DIAGRAM



7.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCP output must be disabled by setting the TRISCCP<2> bit.

Note: If the RB3/CCP1 is configured as an output by clearing the TRISCCP<2> bit, a write to the DCCP bit can cause a capture condition.

7.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

7.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in Operating mode.

7.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 7-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 7-1: CHANGING BETWEEN CAPTURE PRESCALERS

CLRF	CCP1CON	;Turn CCP module off
MOVLW	NEW_CAPT_PS	;Load the W reg with
		; the new prescaler
		; mode value and CCP ON
MOVWF	CCP1CON	;Load CCP1CON with this
		; value

7.3.3 SET-UP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

- 1. Set the PWM period by writing to the PR2 register.
- 2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
- 3. Make the CCP1 pin an output by clearing the TRISCCP<2> bit.
- 4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
- 5. Configure the CCP1 module for PWM operation.

TABLE 7-3:EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 20 MHz

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets	
07h	DATACCP		—	_	—	—	DCCP		DT1CK	xxxx xxxx	xxxx xuxu	
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u	
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0000	-0000	
11h	TMR2	Timer2 Mo	dule's Regis	ter						0000 0000	0000 0000	
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000	
15h	CCPR1L	Capture/C	ompare/PWI		xxxx xxxx	uuuu uuuu						
16h	CCPR1H	Capture/C	Capture/Compare/PWM Register 1 (MSB)								uuuu uuuu	
17h	CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000	
87h	TRISCCP	—	—	—	—	—	TCCP	_	TT1CK	xxxx x1x1	xxxx x1x1	
8Ch	PIE1	_	ADIE	—	—	—	CCP1IE	TMR2IE	TMR1IE	-0000	-0000	
92h	PR2	Timer2 Mo	dule's Perio	d Register						1111 1111	1111 1111	

TABLE 7-4: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Legend: x = unknown, u = unchanged, — = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.

8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). The maximum recommended impedance for analog sources is 10 k Ω . After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, TACQ, see the PIC[®] Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

Note: When the conversion is started, the holding capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL



8.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2Tosc
- 8Tosc
- 32Tosc
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 $\mu s.$

Table 8-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

8.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

- Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.
 - 2: Analog levels on any pin that is defined as a digital input (including the AN3:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 8-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock S	Source (TAD)	Device Frequency						
Operation	ADCS1:ADCS0	20 MHz	5 MHz	1.25 MHz	333.33 kHz			
2Tosc	00	100 ns ⁽²⁾	400 ns ⁽²⁾	1.6 μs	6 µs			
8Tosc	01	400 ns ⁽²⁾	1.6 μs	6.4 μs	24 μs ⁽³⁾			
32Tosc	10	1.6 μs	6.4 μs	25.6 μs ⁽³⁾	96 μs ⁽³⁾			
RC ⁽⁵⁾	11	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ⁽¹⁾			

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 $\mu s.$

- **2:** These values violate the minimum required TAD time.
- **3:** For faster conversion times, the selection of another clock source is recommended.
- 4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for Sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

9.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (to a level of 1.5V-2.1V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified (parameter D004). For a slow rise time, see Figure 9-5.

When the device starts normal operation (exits the Reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

FIGURE 9-5:

RESET CIRCUIT (FOR SLOW VDD POWER-UP)

EXTERNAL POWER-ON



- Def 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
 - **2:** R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
 - **3:** $R1 = 100\Omega$ to $1 k\Omega$ will limit any current flowing into \overline{MCLR} from external capacitor C in the event of \overline{MCLR}/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

9.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter #33), on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A Configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

9.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter #32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

9.7 Brown-Out Reset (BOR)

The PIC16C712/716 members have on-chip Brownout Reset circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V, refer to VBOR parameter D005(VBOR) for a time greater than parameter (TBOR) in Table 12-6. The brown-out situation will reset the chip. A Reset is not guaranteed to occur if VDD falls below 4.0V for less than parameter (TBOR).

On any Reset (Power-on, Brown-out, Watchdog, etc.) the chip will remain in Reset until VDD rises above VBOR. The Power-up Timer will now be invoked and will keep the chip in Reset an additional 72 ms.

If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above VBOR, the Power-Up Timer will execute a 72 ms Reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

For operations where the desired brown-out voltage is other than 4V, an external brown-out circuit must be used. Figure 9-8, 9-9 and 9-10 show examples of external brown-out protection circuits.

9.10.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if bit INTEDG (OPTION_REG<6>) is set, or falling if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the Interrupt Service Routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from Sleep, if bit INTE was set prior to going into Sleep. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See **Section 9.13** "**Power-down Mode** (**Sleep**)" for details on Sleep mode.

9.10.2 TMR0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 4.0 "Timer0 Module")

9.10.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 3.2 "PORTB and the TRISB Register")

9.11 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt, (i.e., W register and STATUS register). This will have to be implemented in software.

Example 9-1 stores and restores the W and STATUS registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

- a) Stores the W register.
- b) Stores the STATUS register in bank 0.
- c) Stores the PCLATH register.
- d) Executes the Interrupt Service Routine code (User-generated).
- e) Restores the STATUS register (and bank select bit).
- f) Restores the W and PCLATH registers.

MOVWF	W TEMP	;Copy W to TEMP register, could be bank one or zero
SWAPF		;Swap status to be saved into W
CLRF	STATUS	; bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF	STATUS_TEMP	Save status to bank zero STATUS_TEMP register
MOVF	PCLATH, W	;Only required if using pages 1, 2 and/or 3
MOVWF	PCLATH_TEMP	;Save PCLATH into W
CLRF	PCLATH	;Page zero, regardless of current page
BCF	STATUS, IRP	Return to Bank 0
MOVF	FSR, W	;Copy FSR to W
MOVWF	FSR_TEMP	;Copy FSR from W to FSR_TEMP
:		
:(ISR)		
:		
MOVF	PCLATH_TEMP, W	;Restore PCLATH
MOVWF	PCLATH	;Move W into PCLATH
SWAPF	STATUS_TEMP,W	;Swap STATUS_TEMP register into W
		;(sets bank to original state)
MOVWF	STATUS	;Move W into STATUS register
SWAPF	W_TEMP,F	;Swap W_TEMP
SWAPF	W_TEMP,W	;Swap W_TEMP into W

EXAMPLE 9-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

WAKE-UP USING INTERRUPTS 9.13.2

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

· If the interrupt occurs before the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the \overline{TO} bit will not be set and \overline{PD} bits will not be cleared.

• If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the \overline{PD} bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the PD bit. If the PD bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a **SLEEP** instruction.



4:

CLKOUT is not available in these osc modes, but shown here for timing reference.

9.14 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	Microchip	does	not	recommend	code			
	protecting windowed devices.							

ID Locations 9.15

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. It is recommended that only the 4 Least Significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

11.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel[®] standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 family of microcontrollers and dsPIC30F family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- · Support for fixed-point and floating-point data
- · Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

11.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC[®] DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, as well as internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent, economical software development tool.

12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

	Standard Operating Conditions (unless otherwise stated)								
DC CHA	RACTER	ISTICS	Operating	g tempe	rature	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial			
						-40°	$C \le TA \le +85^{\circ}C$ for industrial		
Param	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions		
NO.									
D001	Vdd	Supply Voltage	2.5	—	5.5	V			
			VBOR*	—	5.5	V	BOR enabled (Note 7)		
D002*	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5		V			
D003	VPOR	VDD Start Voltage to ensure inter-	—	Vss	—	V	See section on Power-on Reset for details		
		nal Power-on Reset signal							
D004*	SVDD	VDD Rise Rate to ensure internal	0.05	—	—	V/ms	PWRT enabled (PWRTE bit clear)		
D004A*		Power-on Reset signal	TBD	—	—		PWRT disabled (PWRTE bit set)		
							See section on Power-on Reset for details		
D005	VBOR	Brown-out Reset	3.65	—	4.35	V	BODEN bit set		
		voltage trip point							
D010	IDD	Supply Current ^(2,5)	—	2.0	3.8	mA	XT, RC osc modes		
							Fosc = 4 MHz, VDD = 3.0V (Note 4)		
D010A			—	22.5	48	μA	LP osc mode		
							FOSC = 32 kHz, VDD = 3.0V, WDT disabled		
D020	IPD	Power-down Current ^(3,5)	—	7.5	30	μA	VDD = $3.0V$, WDT enabled, $-40^{\circ}C$ to $+85^{\circ}C$		
D021			—	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C		
D021A			—	0.9	5	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$		
		Module Differential Current ⁽⁶⁾							
D022*	∆Iwdt	Watchdog Timer	—	6.0	20	μA	WDTE bit set, VDD = 4.0V		
D022A*	ΔIBOR	Brown-out Reset	_	TBD	200	μA	BODEN bit set, VDD = 5.0V		
1A	Fosc	LP Oscillator Operating Frequency	0	—	200	KHz	All temperatures		
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures		
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures		
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures		

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

 $\underline{OSC1} = external \text{ square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,}$

 \overline{MCLR} = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

PIC16C712/716

FIGURE 12-8: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Param	Sym.	Characteristic			Min.	Typ†	Max.	Units	Conditions
No.									
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet
				With Prescaler	10	—		ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	—		ns	Must also meet
				With Prescaler	10	—	_	ns	parameter 42
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	_	ns	
				With Prescaler	Greater of:	—		ns	N = prescale value
					20 or <u>Tcy + 40</u>				(2, 4,, 256)
			-		N				
45*	Tt1H	T1CKI High Time	Synchronous, F	rescaler = 1	0.5TCY + 20	—	—	ns	Must also meet
			Synchronous,	Standard	15	—		ns	parameter 47
			Prescaler = 2,4,8	Extended (LC)	25	—	—	ns	
			Asynchronous	Standard	30	—		ns	
				Extended (LC)	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, P	Prescaler = 1	0.5TCY + 20	—	_	ns	Must also meet
			Synchronous,	Standard	15	—	—	ns	parameter 47
			Prescaler = 2,4,8	Extended (LC)	25	—	—	ns	
			Asynchronous	Standard	30	—	—	ns	
				Extended (LC)	50	—	_	ns	
47*	Tt1P	T1CKI input period	Synchronous	Standard	Greater of:	—	—	ns	N = prescale value
					30 OR <u>TCY + 40</u>				(1, 2, 4, 8)
					N				
				Extended (LC)	Greater of:				N = prescale value
					50 OR <u>TCY + 40</u>				(1, 2, 4, 8)
					N				
			Asynchronous	Standard	60	—	—	ns	
				Extended (LC)	100	—		ns	
	Ft1	Timer1 oscillator inp	out frequency rar	ige	DC	—	200	kHz	
		(oscillator enabled b	by setting bit T1C	DSCEN)					
48	TCKEZtmr1	Delay from external	clock edge to tir	ner increment	2Tosc	—	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. NOTES: